

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-109613
(43)Date of publication of application : 23.04.1999

(51)Int.Cl. G03F 7/004
G03F 7/004
G03F 7/004
G03F 7/038
G03F 7/039
H01L 21/027
// C08L101/00

(21)Application number : 09-281078
(22)Date of filing : 30.09.1997

(71)Applicant : JSR CORP
(72)Inventor : OTA YOSHIHISA
MATSDA DAIICHI
ISAMOTO YOSHITSUGU

(54) RADIATION SENSITIVE RESIN COMPOSITION

(57) Abstract:

PROBLEM TO BE SOLVED: To obtain a positive or negative radiation sensitive resin compsn. useful as a chemical amplification resist which ensures especially low edge roughness in a fine pattern of $\leq 0.2 \mu\text{m}$ and has high sensitivity and high resolution.

SOLUTION: The positive radiation sensitive resin compsn. contains a fullerene deriv. soluble in a solvent for a resist, a radiation sensitive acid generating agent and an acid dissociable group-contg. resin or an alkali-soluble resin and an alkali solubility controlling agent. The negative radiation sensitive resin compsn. contains the fullerene deriv., the radiation sensitive acid generating agent, an alkali-soluble resin and a compd. capable of crosslinking the alkali- soluble resin in the presence of an acid.

LEGAL STATUS

[Date of request for examination] 27.09.2002

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted.registration]

[Date of final disposal for application]

[Patent number] 3521710

[Date of registration] 20.02.2004

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C) 1998-2003, Japan Patent Office